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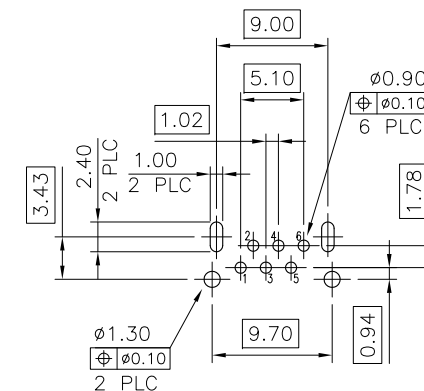
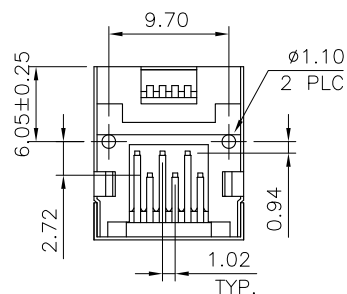
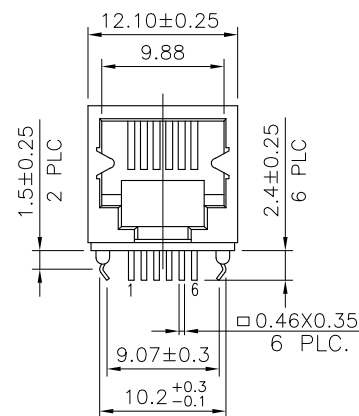
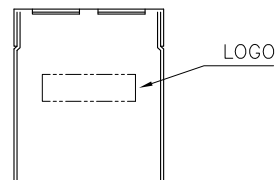
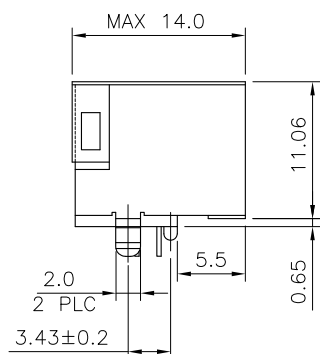
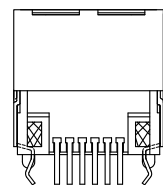
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LOC
DWDIST
—

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	A2	ECR-12-012115	26OCT12	EL	WK



RECOMMENDED PCB LAYOUT (THICKNESS: 1.6mm)
DIMENSION TOLERANCE: 1 PLC: ±0.1 2PLC: ±0.05

NOTE:

- MATERIAL:
HOUSING: PA46 WITH 30% GF, UL94 V-0, BLACK COLOR.
CONTACTS: PHOSPHOR BRONZE.
SHIELD: BRASS.
- FINISH:
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27μm [50μ"] MIN. NICKEL.
SHIELD: 0.51μm [20μ"] MIN. NICKEL PLATED.
- WAVE SOLDER CAPABLE TO 265°C PER 109-202, CONDITION B.

4. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

OBSOLETE	6P2C	REEL	1.27μm [50μ"]	2-1734723-8
			0.762μm [30μ"]	2-1734723-7
			0.381μm [15μ"]	2-1734723-6
			0.152μm [6μ"]	2-1734723-5
OBSOLETE	6P2C	TRAY	1.27μm [50μ"]	2-1734723-4
			0.762μm [30μ"]	2-1734723-3
			0.381μm [15μ"]	2-1734723-2
			0.152μm [6μ"]	2-1734723-1
OBSOLETE	6P6C	REEL	1.27μm [50μ"]	-1734723-8
			0.762μm [30μ"]	-1734723-7
			0.381μm [15μ"]	1734723-6
			0.152μm [6μ"]	-1734723-5
OBSOLETE	6P6C	TRAY	1.27μm [50μ"]	-1734723-4
			0.762μm [30μ"]	-1734723-3
			0.381μm [15μ"]	-1734723-2
			0.152μm [6μ"]	1734723-1
	RJ11	PACKAGE	MIN. GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN	A. WU	10MAR2008
CHK	S. HOU	10MAR2008
APVD	W. KODAMA	10MAR2008
PRODUCT SPEC	108-57527	
APPLICATION SPEC	—	
WEIGHT	3 GRAMS	
CUSTOMER DRAWING		



TE Connectivity

MODULAR JACK, RJ11,
SINGLE, DIP TYPE

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	—	©=1734723	—
SCALE	—	SHEET 1 OF 5	REV A2

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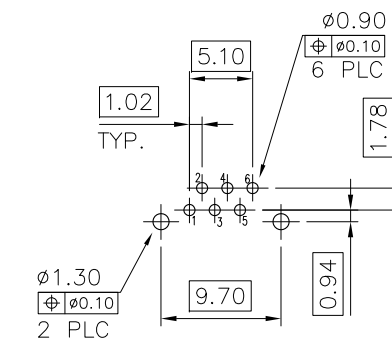
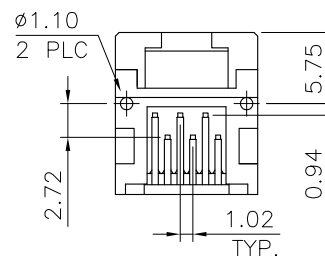
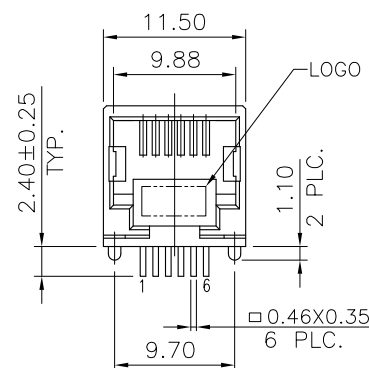
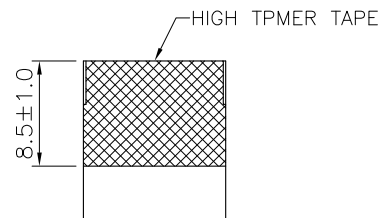
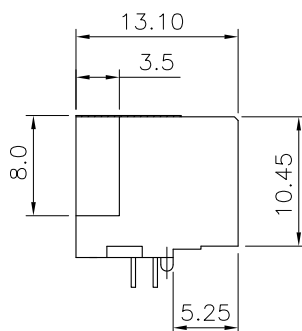
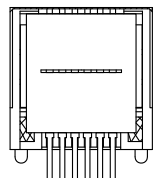
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LOC
DWDIST
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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
		SEE SHEET 1.			



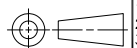
RECOMMENDED PCB LAYOUT (THICKNESS: 1.6mm)
DIMENSION TOLERANCE: 1 PLC: ±0.1 2PLC: ±0.05

NOTE:

- MATERIAL:
HOUSING: PA46 WITH 30% GF, UL94 V-0, BLACK COLOR.
CONTACTS: PHOSPHOR BRONZE.
SHIELD: BRASS.
- FINISH:
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27μm [50μ"] MIN. NICKEL.
- WAVE SOLDER CAPABLE TO 265°C PER 109-202, CONDITION B.

4. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

OBSOLETE	6P6C	REEL	1.27μm [50μ"]	1-1734723-8
			0.762μm [30μ"]	1-1734723-7
			0.381μm [15μ"]	1-1734723-6
			0.152μm [6μ"]	1-1734723-5
OBSOLETE	6P6C	TRAY	1.27μm [50μ"]	1-1734723-4
			0.762μm [30μ"]	1-1734723-3
			0.381μm [15μ"]	1-1734723-2
			0.152μm [6μ"]	1-1734723-1
	RJ11	PACKAGE	MIN. GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN A. WU 10MAR2008	 TE Connectivity	
DIMENSIONS: MM		CHK S. HOU 10MAR2008		
		APVD W. KODAMA 10MAR2008		
		PRODUCT SPEC 108-57527		
MATERIAL SEE NOTE		APPLICATION SPEC —	NAME MODULAR JACK, RJ11, SINGLE, DIP TYPE	
FINISH SEE NOTE		WEIGHT 2.5 GRAMS	SIZE A3	RESTRICTED TO —
		CUSTOMER DRAWING	SCALE —	SHEET 2 OF 5
			REV A2	

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LOC

DIST

REVISIONS

DW

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P

LTR

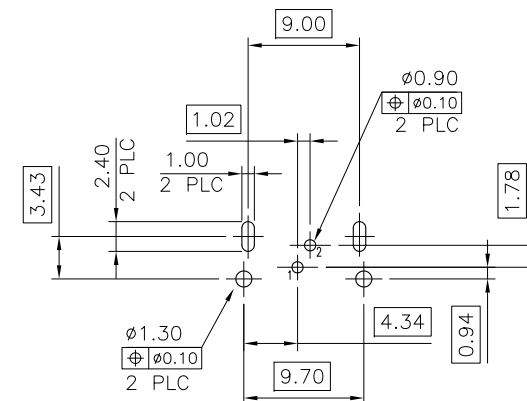
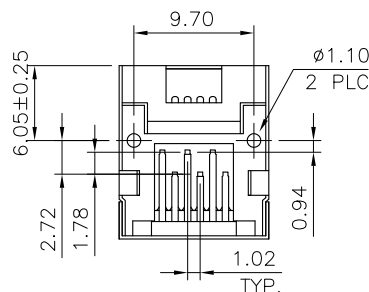
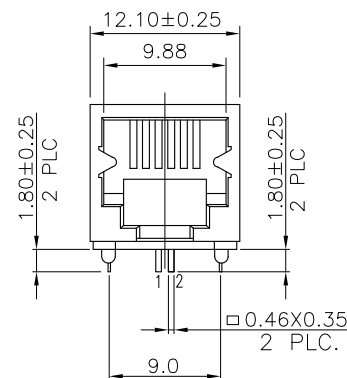
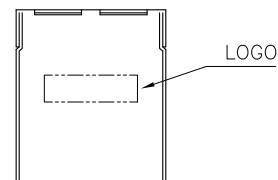
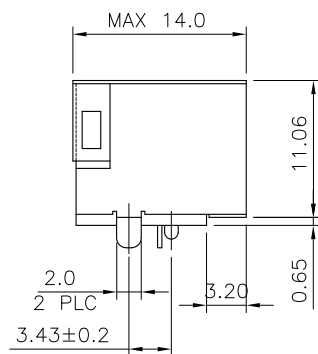
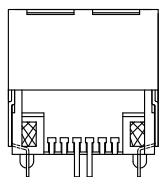
DESCRIPTION

DATE

DWN

APVD

SEE SHEET 1.

RECOMMENDED PCB LAYOUT (THICKNESS: 1.6mm)
DIMENSION TOLERANCE: 1 PLC: ±0.1 2PLC: ±0.05

NOTE:

- MATERIAL:
HOUSING: PA46 WITH 30% GF, UL94 V-0, BLACK COLOR.
CONTACTS: PHOSPHOR BRONZE.
SHIELD: BRASS.
- FINISH:
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27μm [50μ"] MIN. NICKEL.
SHIELD: 0.51μm [20μ"] MIN. NICKEL PLATED.
- WAVE SOLDER CAPABLE TO 265°C PER TE TEST SPEC. 109-202, CONDITION B.

OBSOLETE	6P2C	REEL	1.27μm [50μ"]	4-1734723-8
			0.762μm [30μ"]	4-1734723-7
			0.381μm [15μ"]	4-1734723-6
			0.152μm [6μ"]	4-1734723-5
OBSOLETE		TRAY	1.27μm [50μ"]	4-1734723-4
			0.762μm [30μ"]	4-1734723-3
			0.381μm [15μ"]	4-1734723-2
			0.152μm [6μ"]	4-1734723-1
	RJ11	PACKAGE	MIN. GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN A. WU 10MAR2008

CHK S. HOU 10MAR2008

APVD W. KODAMA 10MAR2008

PRODUCT SPEC

108-57527

APPLICATION SPEC

—

WEIGHT 3 GRAMS

CUSTOMER DRAWING



TE Connectivity

NAME

MODULAR JACK, RJ11,
SINGLE, DIP TYPE

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

—

C=1734723

—

SCALE —

SHEET

3 OF 5

REV A2

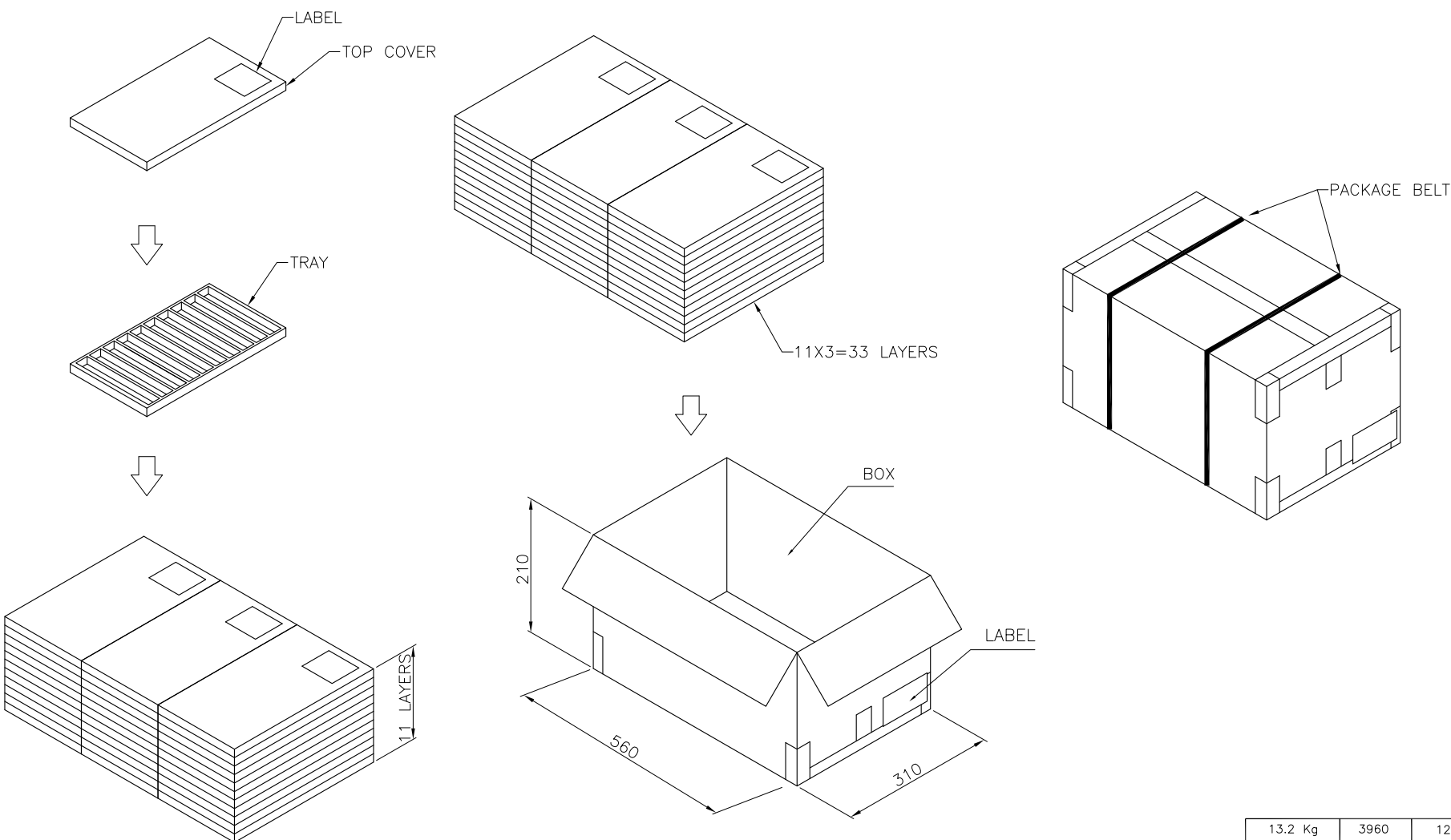
4

3

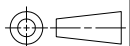
2

1

LOC	DIST	REVISIONS					
DW	—	P	LTR	DESCRIPTION	DATE	DWN	APVD
				SEE SHEET 1.			



13.2 Kg	3960	120	1734723-1
GROSS WEIGHT	TOTAL	PCS/TRAY	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN A. WU	10MAR2008	 TE Connectivity			
		CHK S. HOU	10MAR2008				
		APVD W. KODAMA	10MAR2008				
DIMENSIONS: MM		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME			
		0 PLC ± -		MODULAR JACK, RJ11, SINGLE, DIP TYPE			
		1 PLC ± -					
		2 PLC ± -					
		3 PLC ± -					
4 PLC ± -		PRODUCT SPEC		SIZE CAGE CODE DRAWING NO RESTRICTED TO			
APPLICATION SPEC							
WEIGHT							
MATERIAL		FINISH		A3 - C=1734723			
		CUSTOMER DRAWING		SCALE		SHEET	REV
				-		4 of 5	A2

